CY54FCT157T, CY74FCT157T QUAD 2-INPUT MULTIPLEXERS WITH 3-STATE OUTPUTS

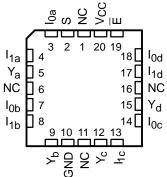
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- Function, Pinout, and Drive Compatible With FCT and F Logic
- Reduced V_{OH} (Typically = 3.3 V) Versions of Equivalent FCT Functions
- Edge-Rate Control Circuitry for Significantly Improved Noise Characteristics
- I_{off} Supports Partial-Power-Down Mode Operation
- Matched Rise and Fall Times
- Fully Compatible With TTL Input and Output Logic Levels
- ESD Protection Exceeds JESD 22

 2000-V Human-Body Model (A114-A)
 - 200-V Human-Body Model (A114-A - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)
- CY54FCT157T
 - 32-mA Output Sink Current
 - 12-mA Output Source Current
- CY74FCT157T
 64-mA Output Sink Current
 - 32-mA Output Source Current
- 3-State Outputs

CY74FCT157T . . . Q OR SO PACKAGE (TOP VIEW) 16 Vcc S 15 🛛 Ē I_{0a} 2 I_{1a} 3 14 | I_{0d} 13 🛛 I_{1d} Y_a [4 12 🛛 Y_d l_{0b} 5 11 [] I_{0c} I_{1b} 6 10 🛛 I_{1c} Y_b [7 9[] Y_c GND 8

CY54FCT157T...L PACKAGE (TOP VIEW)



description

NC - No internal connection

The 'FCT157T devices are quad two-input multiplexers that select four bits of data from two sources under the control of a common data-select (S) input. The output-enable (\overline{E}) input is active low. When \overline{E} is high, all of the outputs (Y) are forced low, regardless of all other input conditions.

Moving data from two groups of registers to four common output buses is a common use of the 'FCT157T devices. The state of S determines the particular register from which the data comes. It also can be used as a function generator. These devices are useful for implementing highly irregular logic by generating any 4 of the 16 different functions of 2 variables, with 1 variable common.

The 'FCT157T devices are logic implementations of a four-pole, two-position switch, where the position of the switch is determined by the logic levels at S.

These devices are fully specified for partial-power-down applications using I_{off}. The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.



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PIN DESCRIPTION

| NAME | DESCRIPTION |
|----------------|----------------------------|
| S | Common select input |
| Ē | Enable inputs (active low) |
| I ₀ | Data inputs from source 0 |
| I ₁ | Data inputs from source 1 |
| Y | Noninverted outputs |

ORDERING INFORMATION

| TA | PAC | (AGE [†] | SPEED (ns) | ORDERABLE PART NUMBER | TOP-SIDE MARKING |
|----------------|-----------|-------------------|---------------|--------------------------|---------------------|
| | QSOP – Q | Tape and reel | 4.3 | CY74FCT157CTQCT | FT157-3 |
| | SOIC – SO | Tube | 4.3 | CY74FCT157CTSOC | FCT157C |
| –40°C to 85°C | 3010 - 30 | Tape and reel | 4.3 | CY74FCT157CTSOCT | FCT157C |
| -40 C 10 85 C | QSOP – Q | Tape and reel | 5 | CY74FCT157ATQCT | FT157-1 |
| | SOIC – SO | Tube | 5 | CY74FCT157ATSOC | FCT157A |
| | 3010 - 30 | Tape and reel | 5 | CY74FCT157ATSOCT | FCT157A |
| –55°C to 125°C | LCC – L | Tube | 5.8 | CY54FCT157ATLMB | |

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

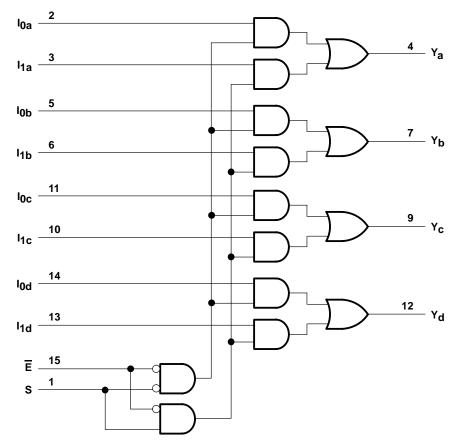
| | FU | NCTION | TABLE | |
|---|-----|--------|----------------|---|
| | INP | | OUTPUT | |
| Ē | S | I0 | l ₁ | Y |
| Н | Х | Х | Х | L |
| L | Н | Х | L | L |
| L | Н | Х | н | н |
| L | L | L | х | L |
| L | L | Н | Х | Н |

FUNCTION TABLE

H = High logic level, L = Low logic level, X = Don't care



logic diagram (positive logic)



Pin numbers shown are for the Q and SO packages.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

| Supply voltage range to ground potential | –0.5 V to 7 V |
|--|------------------------|
| DC input voltage range | –0.5 V to 7 V |
| DC output voltage range | \ldots –0.5 V to 7 V |
| DC output current (maximum sink current/pin) | 120 mA |
| Package thermal impedance, θ_{JA} (see Note 1): Q package | 90°C/W |
| SO package | 57°C/W |
| Ambient temperature range with power applied, T _A | –65°C to 135°C |
| Storage temperature range, T _{stg} | –65°C to 150°C |

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The package thermal impedance is calculated in accordance with JESD 51-7.



recommended operating conditions (see Note 2)

| | | CY | 54FCT15 | 7T | CY | CY74FCT157T | | |
|----------------|--------------------------------|-----|---------|-----|------|-------------|------|------|
| | | MIN | NOM | MAX | MIN | NOM | MAX | UNIT |
| VCC | Supply voltage | 4.5 | 5 | 5.5 | 4.75 | 5 | 5.25 | V |
| VIH | High-level input voltage | 2 | | | 2 | | | V |
| VIL | Low-level input voltage | | | 0.8 | | | 0.8 | V |
| ЮН | High-level output current | | | -12 | | | -32 | mA |
| IOL | Low-level output current | | | 32 | | | 64 | mA |
| Т _А | Operating free-air temperature | -55 | | 125 | -40 | | 85 | °C |

NOTE 2: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

| | TEST CONDITIONS | CY | '54FCT15 | 57T | CY | 74FCT15 | 57T | |
|------------------|--|-----|----------|------|-----|---------|------|-------|
| PARAMETER | TEST CONDITIONS | MIN | TYP† | MAX | MIN | түр† | MAX | UNIT |
| Maria | V _{CC} = 4.5 V, I _{IN} = -18 mA | | -0.7 | -1.2 | | | | V |
| VIK | $V_{CC} = 4.75 \text{ V}, I_{IN} = -18 \text{ mA}$ | | | | | -0.7 | -1.2 | V |
| | $V_{CC} = 4.5 \text{ V}, \qquad I_{OH} = -12 \text{ mA}$ | 2.4 | 3.3 | | | | | |
| VOH | $V_{CC} = 4.75 V$ $I_{OH} = -32 mA$ | | | | 2 | | | V |
| | $I_{OH} = -15 \text{ mA}$ | | | | 2.4 | 3.3 | | |
| VOL | $V_{CC} = 4.5 \text{ V}, \qquad I_{OL} = 32 \text{ mA}$ | | 0.3 | 0.55 | | | | v |
| VOL | $V_{CC} = 4.75 \text{ V}, I_{OL} = 64 \text{ mA}$ | | | | | 0.3 | 0.55 | v |
| V _{hys} | All inputs | | 0.2 | | | 0.2 | | V |
| łı | $V_{CC} = 5.5 \text{ V}, \qquad V_{IN} = V_{CC}$ | | | 5 | | | | μA |
| 1 | $V_{CC} = 5.25 \text{ V}, V_{IN} = V_{CC}$ | | | | | | 5 | μΛ |
| ΊΗ | $V_{CC} = 5.5 \text{ V}, \qquad V_{IN} = 2.7 \text{ V}$ | | | ±1 | | | | μA |
| ΠΗ | $V_{CC} = 5.25 \text{ V}, V_{IN} = 2.7 \text{ V}$ | | | | | | ±1 | μΛ |
| ١ _{IL} | $V_{CC} = 5.5 \text{ V}, \qquad V_{IN} = 0.5 \text{ V}$ | | | ±1 | | | | μA |
| ΊL | $V_{CC} = 5.25 \text{ V}, V_{IN} = 0.5 \text{ V}$ | | | | | | ±1 | μι |
| IOZH | V _{CC =} 5.5 V, V _{OUT} = 2.7 V | | | 10 | | | | μA |
| 'UZH | V _{CC =} 5.25 V, V _{OUT} = 2.7 V | | | | | | 10 | μ. |
| IOZL | V _{CC} = 5.5 V, V _{OUT} = 0.5 V | | | -10 | | | | μA |
| -OZL | V _{CC} = 5.25 V, V _{OUT} = 0.5 V | | | | | | -10 | μι |
| los‡ | V _{CC} = 5.5 V, V _{OUT} = 0 V | -60 | -120 | -225 | | | | mA |
| -03- | V _{CC} = 5.25 V, V _{OUT} = 0 V | | | | -60 | -120 | -225 | |
| loff | V _{CC} = 0 V, V _{OUT} = 4.5 V | | | ±1 | | | ±1 | μΑ |
| ICC | $V_{CC} = 5.5 \text{ V}, \qquad V_{IN} \le 0.2 \text{ V}, \qquad V_{IN} \ge V_{IN} \ge 1000 \text{ V}$ | | 0.1 | 0.2 | | | | mA |
| .00 | $V_{CC} = 5.25 \text{ V}, V_{IN} \le 0.2 \text{ V}, V_{IN} \ge V_{IN} \ge 0.2 \text{ V}$ | | | | | 0.1 | 0.2 | |
| 100 | V_{CC} = 5.5 V, V_{IN} = 3.4 V§, $~f_1$ = 0, Outputs ope | n | 0.5 | 2 | | | | mA |
| ∆ICC | $V_{CC} = 5.25 \text{ V}, \text{ V}_{IN} = 3.4 \text{ V}^{\$}, \text{ f}_1 = 0, \text{ Outputs op}$ | en | | | | 0.5 | 2 | III/A |

[†] Typical values are at $V_{CC} = 5 V$, $T_A = 25^{\circ}C$.

* Not more than one output should be shorted at a time. Duration of short should not exceed one second. The use of high-speed test apparatus and/or sample-and-hold techniques are preferable to minimize internal chip heating and more accurately reflect operational values. Otherwise, prolonged shorting of a high output can raise the chip temperature well above normal and cause invalid readings in other parametric tests. In any sequence of parameter tests, IOS tests should be performed last.

§ Per TTL-driven input (V_{IN} = 3.4 V); all other inputs at V_{CC} or GND



CY54FCT157T, CY74FCT157T **QUAD 2-INPUT MULTIPLEXERS** WITH 3-STATE OUTPUTS

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted) (continued)

| | | TEST CONDITION | 0 | CY | 54FCT1 | 57T | CY | 74FCT15 | 7 T | |
|-----------|--|---|---|-----|--------|-------|------|---------|------------|-----|
| PARAMETER | | түр† | MAX | MIN | түр† | MAX | UNIT | | | |
| 1¶ | | te input switching at 50 = GND, $V_{IN} \le 0.2 V$ of | | | 0.06 | 0.12 | | | | mA/ |
| ICCD | | ne input switching at 5 = GND, $V_{IN} \le 0.2$ V of | | | | | | 0.06 | 0.12 | MHz |
| | | One input switching at $f_1 = 10 \text{ MHz}$ | $\begin{array}{l} V_{IN} \leq 0.2 \text{ V or} \\ V_{IN} \geq V_{CC} - 0.2 \text{ V} \end{array}$ | | 0.7 | 1.4 | | | | |
| | V _{CC} = 5.5 V, Outputs open, | at 50% duty cycle | V_{IN} = 3.4 V or GND | | 1 | 2.4 | | | | |
| | $\overline{E} = GND$ | Four bits switching at $f_1 = 2.5$ MHz | $V_{IN} \le 0.2 \text{ V or}$ $V_{IN} \ge V_{CC} - 0.2 \text{ V}$ | | 0.7 | 1.4 | | | | |
| IC# | | at 50% duty cycle | $V_{IN} = 3.4 \text{ V or GND}$ | | 1.7 | 5.4ll | | | | mA |
| 10.11 | | One input switching | $\begin{array}{l} V_{IN} \leq 0.2 \ V \ or \\ V_{IN} \geq V_{CC} - 0.2 \ V \end{array}$ | | | | | 0.7 | 1.4 | ША |
| | V _{CC} = 5.25 V, Outputs open, | at f ₁ = 10 MHz at 50% duty cycle | V_{IN} = 3.4 V or GND | | | | | 1 | 2.4 | |
| | $\overline{E} = GND$ | Four bits switching at $f_1 = 2.5$ MHz | $V_{IN} \le 0.2 \text{ V or}$ $V_{IN} \ge V_{CC} - 0.2 \text{ V}$ | | | | | 0.7 | 1.4 | |
| | | at 50% duty cycle | $V_{IN} = 3.4 \text{ V or GND}$ | | | | | 1.7 | 5.4 | |
| Ci | | | | | 5 | 10 | | 5 | 10 | pF |
| Co | | | | | 9 | 12 | | 9 | 12 | pF |

[†] Typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

¶ This parameter is derived for use in total power-supply calculations.

[#]IC $= I_{CC} + \Delta I_{CC} \times D_H \times N_T + I_{CCD} (f_0/2 + f_1 \times N_1)$

Where:

- IC = Total supply current
- I_{CC} = Power-supply current with CMOS input levels
- ΔI_{CC} = Power-supply current for a TTL high input (V_{IN} = 3.4 V)
- D_H = Duty cycle for TTL inputs high NT = Number of TTL inputs at D_H
- I_{CCD} = Dynamic current caused by an input transition pair (HLH or LHL)
- f₀ = Clock frequency for registered devices, otherwise zero
- f1 = Input signal frequency
- N_1 = Number of inputs changing at f1
- All currents are in milliamperes and all frequencies are in megahertz.

Il Values for these conditions are examples of the I_{CC} formula.

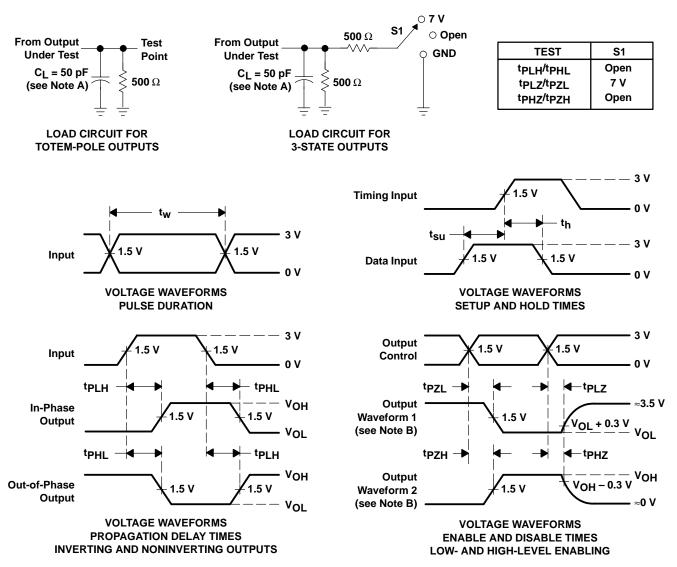
switching characteristics over operating free-air temperature range (see Figure 1)

| PARAMETER | FROM | то | CY54FC | T157AT | CY74FC | T157AT | CY74FC1 | 157CT | UNIT |
|------------------|---------|----------|--------|--------|--------|--------|---------|-------|------|
| PARAMETER | (INPUT) | (OUTPUT) | MIN | MAX | MIN | MAX | MIN | MAX | UNIT |
| ^t PLH | | V | 1.5 | 5.8 | 1.5 | 5 | 1.5 | 4.3 | |
| ^t PHL | Ι | T | 1.5 | 5.8 | 1.5 | 5 | 1.5 | 4.3 | ns |
| ^t PLH | Ē | V | 1.5 | 7.4 | 1.5 | 6 | 1.5 | 4.8 | ns |
| ^t PHL | Ľ | Ι | 1.5 | 7.4 | 1.5 | 6 | 1.5 | 4.8 | 115 |
| ^t PLH | s | V | 1.5 | 8.1 | 1.5 | 7 | 1.5 | 5.2 | ns |
| ^t PHL | 5 | | 1.5 | 8.1 | 1.5 | 7 | 1.5 | 5.2 | 115 |



CY54FCT157T, CY74FCT157T QUAD 2-INPUT MULTIPLEXERS WITH 3-STATE OUTPUTS

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PARAMETER MEASUREMENT INFORMATION

NOTES: A. C_L includes probe and jig capacitance.

 B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 C. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms





PACKAGING INFORMATION

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead finish/ Ball material | MSL Peak Temp | Op Temp (°C) | Device Marking (4/5) | Samples |
|------------------|---------------|--------------|--------------------|------|----------------|---------------------|-------------------------------|---------------------|--------------|-------------------------|---------|
| | | | | | | | (6) | | | | |
| 5962-9220803M2A | ACTIVE | LCCC | FK | 20 | 1 | Non-RoHS & Green | SNPB | N / A for Pkg Type | -55 to 125 | 5962- 9220803M2A | Samples |
| CY74FCT157ATDR | ACTIVE | SOIC | D | 16 | 2500 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 85 | FCT157AT | Samples |
| CY74FCT157ATSOC | ACTIVE | SOIC | DW | 16 | 40 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 85 | FCT157A | Samples |
| CY74FCT157CTD | ACTIVE | SOIC | D | 16 | 40 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 85 | FCT157CT | Samples |
| CY74FCT157CTQCT | ACTIVE | SSOP | DBQ | 16 | 2500 | RoHS & Green | NIPDAU | Level-2-260C-1 YEAR | -40 to 85 | FT157-3 | Samples |
| CY74FCT157CTSOC | ACTIVE | SOIC | DW | 16 | 40 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 85 | FCT157C | Samples |
| CY74FCT157CTSOCT | ACTIVE | SOIC | DW | 16 | 2000 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 85 | FCT157C | Samples |

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <= 1000ppm threshold. Antimony trioxide based flame retardants must also meet the <= 1000ppm threshold requirement.

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.



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PACKAGE OPTION ADDENDUM

9-Mar-2021

⁽⁶⁾ Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



| *All dimensions are nominal | | | | | | | | | | | | |
|-----------------------------|-----------------|--------------------|----|------|--------------------------|--------------------------|------------|------------|------------|------------|-----------|------------------|
| Device | Package Type | Package Drawing | | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
| CY74FCT157ATDR | SOIC | D | 16 | 2500 | 330.0 | 16.4 | 6.5 | 10.3 | 2.1 | 8.0 | 16.0 | Q1 |
| CY74FCT157CTQCT | SSOP | DBQ | 16 | 2500 | 330.0 | 12.5 | 6.4 | 5.2 | 2.1 | 8.0 | 12.0 | Q1 |
| CY74FCT157CTSOCT | SOIC | DW | 16 | 2000 | 330.0 | 16.4 | 10.75 | 10.7 | 2.7 | 12.0 | 16.0 | Q1 |



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PACKAGE MATERIALS INFORMATION

5-Jan-2022



*All dimensions are nominal

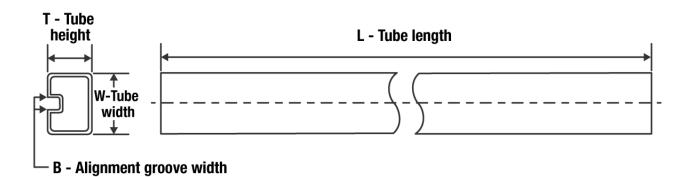
| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|------------------|--------------|-----------------|------|------|-------------|------------|-------------|
| CY74FCT157ATDR | SOIC | D | 16 | 2500 | 340.5 | 336.1 | 32.0 |
| CY74FCT157CTQCT | SSOP | DBQ | 16 | 2500 | 340.5 | 338.1 | 20.6 |
| CY74FCT157CTSOCT | SOIC | DW | 16 | 2000 | 350.0 | 350.0 | 43.0 |



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TUBE



*All dimensions are nominal

| Device | Package Name | Package Type | Pins | SPQ | L (mm) | W (mm) | Τ (μm) | B (mm) |
|-----------------|--------------|--------------|------|-----|--------|--------|--------|--------|
| 5962-9220803M2A | FK | LCCC | 20 | 1 | 506.98 | 12.06 | 2030 | NA |
| CY74FCT157ATSOC | DW | SOIC | 16 | 40 | 506.98 | 12.7 | 4826 | 6.6 |
| CY74FCT157CTD | D | SOIC | 16 | 40 | 507 | 8 | 3940 | 4.32 |
| CY74FCT157CTSOC | DW | SOIC | 16 | 40 | 506.98 | 12.7 | 4826 | 6.6 |

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